**Thermoelectric module (TM) specification**

<table>
<thead>
<tr>
<th>PO position #</th>
<th>TM</th>
<th>Internal Solder Melting Temp, °C</th>
<th>Max operating temperature, °C</th>
<th>Parameters in vacuum at hot side temperature 25 °C</th>
<th>Rac at 25 °C</th>
<th>Ceramic size, mm</th>
<th>TM Height</th>
<th>Wire</th>
<th>Sealing</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>2-067-04-12</td>
<td>138</td>
<td>130</td>
<td>115</td>
<td>0.8</td>
<td>5.8</td>
<td>1.2</td>
<td>101</td>
<td>8.14</td>
</tr>
</tbody>
</table>

**Clamping force:** 0.5 - 0.9 kg
Max dT is reduced by 3-4K for silicon sealed and 2-3K for epoxy sealed versions.

![Graph of Q(dT) at Thot=298K](image)